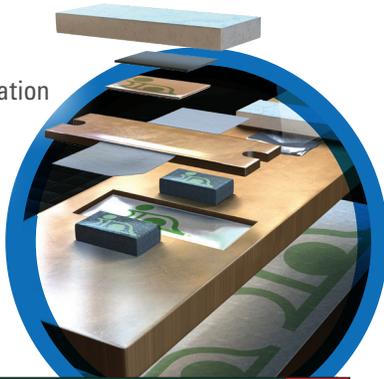


Why Gold for Die-Attach?

- Flux-free high-reliability process
- Highest tensile strength of any solder
- Superior thermal conductivity
- Good joint strength
- High melting point is compatible with subsequent reflow processes
- Resistance to corrosion
- Excellent wetting properties
- Superior thermal fatigue resistance
- Resistance to oxidation
- Pb-free and RoHS compliant



Indalloy®	Composition
200	100Au (1,064°C Eutectic)
Braze B962	99.99Ag (962°C Eutectic)
193	72Ag28Cu (780°C Eutectic)
B6851	63Ag27Cu/10In (685/730°C)
178	82Au18In (451/485°C)
NA	96.8Au3.2Si (363°C Eutectic)
183	88Au12Ge (356°C Eutectic)
270	75Au25Sn (278/331°C)
269	78Au22Sn (278/301°C)
271	79Au21Sn (278/289°C)
182	80Au20Sn (278°C Eutectic)

From One Engineer To Another®



Need it Quickly? Gold Preform Quick Turn Program

Indium Corporation's Gold Preform **Quick Turn** Program is designed to get parts in your hands quicker than ever. By doing this, we decrease the time needed to get your project started and increase your production opportunities.

- Designed to deliver parts quickly and affordably
- New design, new tool, prototype quantities in 2–3 weeks
- Engineering support from design to production



Contact our engineers: askus@indium.com

Learn more: www.indium.com

From One Engineer To Another®

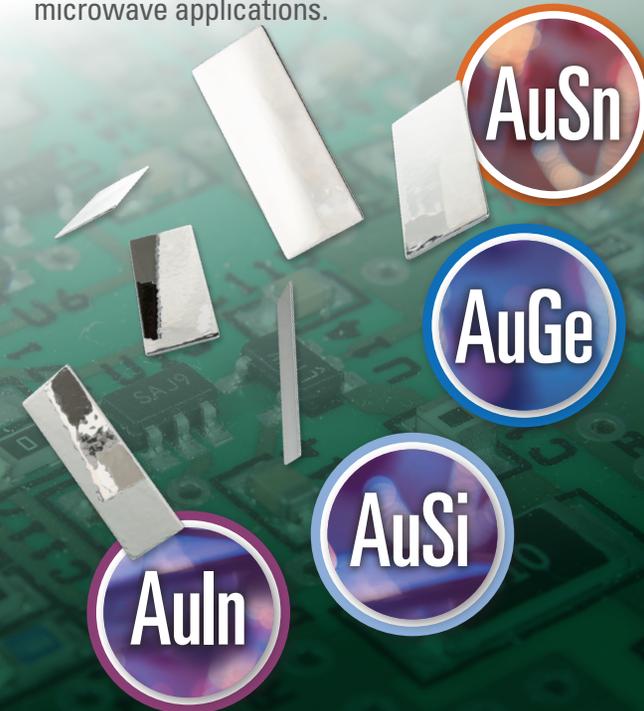
All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Form No. 99988 R2

High-Reliability Precision Die-Attach (PDA) Preforms for Critical Laser and RF Applications

Indium Corporation is the leading solder supplier for laser and optical and RF microwave applications.



We Believe that **MATERIALS SCIENCE** Changes the World



High-Reliability Precision Die-Attach (PDA) Preforms

for Critical Laser and RF Applications

Gold-Based Precision Die-Attach Preforms

Highly accurate solder volume and BLT control

Precision edge quality

Flat and free of warping or bends

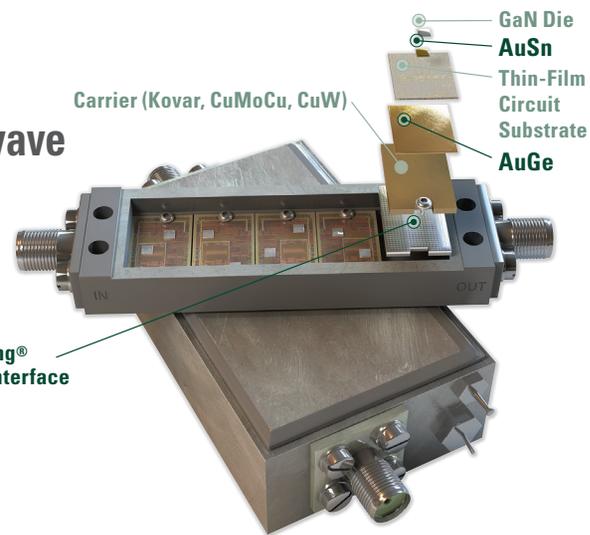
Optimized cleanliness control

Default waffle pack method

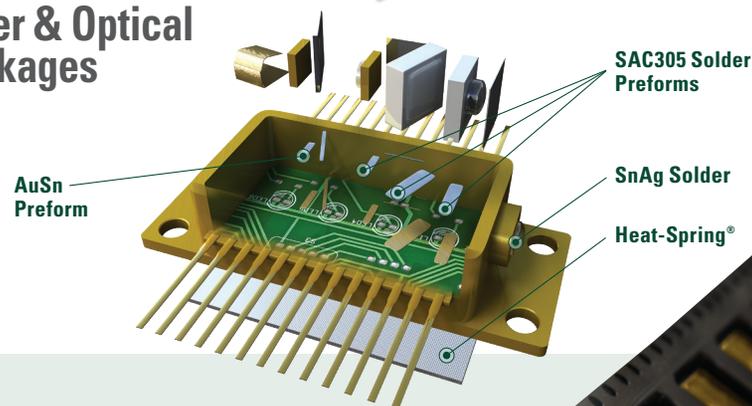
Primary alloys available:
• 80Au/20Sn • 79Au/21Sn

Development alloys available:
• 78Au/22Sn • 77Au/23Sn • 76Au/24Sn
• 75Au/25Sn • 88Au/12Ge • 96.8Au/3.2Si
• 82Au/18In

RF Microwave Packages



Laser & Optical Packages



Packaging Options

Waffle pack is the default pack method for our Precision Die-Attach Preforms. However, our other packaging options include bulk pack, layer pack, and tape & reel. Additionally, we can create customized packaging solutions to meet your needs.

